

PRODUCT DATA SHEET



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Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.



B5817W/B5818W/B5819W

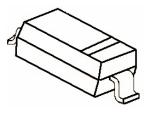
SOD-123 Plastic-Encapsulate Schottky Barrier Diode

Features

- High Current Capability
- Low Forward Voltage Drop

Mechanical Data

- SOD-123 Small Outline Plastic Package
- Polarity: Color band denotes cathode end
- Epoxy UL: 94V-0
- Mounting Position: Any



SOD-123

Maximum Ratings & Thermal Characteristics	(Ratings at 25° C ambient temperature unless otherwise specified.)
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Parameters	Symbol	B5817W	B5818W	B5819W	Unit
Maximum repetitive peak reverse voltage	VRRM	20	30	40	V
Maximum RMS voltage	VRMS	14	21	28	V
Maximum DC blocking voltage	VDC	20	30	40	V
Maximum average forward rectified current	lfм	1.0			А
Peak forward surge current 8.3 ms single half sine-wave	IFSM	9			А
Typical thermal resistance	Reja	250		°C /W	
Power Dissipation	PD	500		mW	
Storage temperature range	TSTG	-50-+150			°C

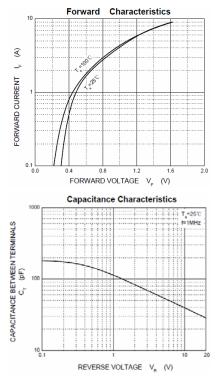
Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified).

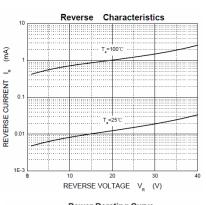
Parameters	Symbol	Test conditions	B5817W	B5818W	B5819W	单位 Unit
Maximum forward voltage	VF	IF = 1.0A IF = 3.0A	0.480 0.750	0.550 0.875	0.600 1.000	V
Maximum reverse breakdown voltage	VR	IR=1mA	20	30	40	V
Maximum reverse current	lr	VR=20V B5817W VR=30V B5818W VR=40V B5819W		1.0	1	mA
Type junction capacitance	Cj	VR = 4.0V, f = 1MHz		110		pF

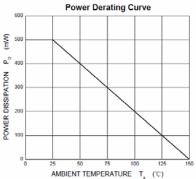


B5817W/B5818W/B5819W

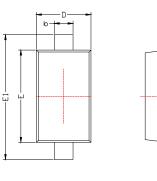
Characteristic Curves

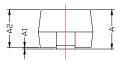






SOD-123 PACKAGE OUTLINE Plastic surface mounted package





SYMBOL	DIMENSIONS		
SIMBUL	MIN.	MAX.	
A	1.050	1.250	
A1	0.000	0.100	
A2	1.050	1.150	
b	0.450	0.650	
C	0.080	0.150	
D	1.500	1.700	
E	2.600	2.800	
E1	3.550	3.850	
L	0.500REF		
L1	0.250	0.450	
θ	0*	8°	





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